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This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (canceled).

Claim 9 (original): A manufacturing method of a chip-type composite electronic component comprising the steps of:

forming an inductor characteristic sheet by laminating a ceramic layer having an internal coil conductor;

forming a thermistor characteristic sheet by laminating a ceramic layer having an internal electrode and having a predetermined resistance-temperature characteristic;

forming a compound multilayer body by adhering the inductor characteristic sheet and the thermistor characteristic sheet by pressure with a diffusion-prevention layer sandwiched therebetween;

baking a compound multilayer body;

forming external electrodes on an end surface of a compound multilayer body in which at least one end part of an internal coil conductor and at least one end part of an internal electrode are exposed.

Claim 10 (original): A manufacturing method of a chip-type composite electronic component according to Claim 9, wherein one end of the internal coil conductor of the inductor is connected to one of the external electrodes, one end of the internal electrode of the thermistor is connected to the other of the external electrodes, and the other end of the internal coil conductor of the inductor and the other end of the internal electrode of the thermistor are connected together.

Claim 11 (original): A manufacturing method of a chip-type composite electronic

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component according to Claim 9, further comprising the steps of connecting one end of the internal coil conductor of the inductor and one end of the internal electrode of the thermistor to one of the external electrodes, and connecting the other end of the internal coil conductor of the inductor and the other end of the internal electrode of the thermistor to the other of the external electrodes.

Claim 12 (original): A manufacturing method of a chip-type composite electronic component according to Claim 9, wherein the thermistor is a negative-characteristic thermistor.

Claim 13 (original): A manufacturing method of a chip-type composite electronic component according to Claim 9, wherein the thermistor is a positive-characteristic thermistor.

Claim 14 (original): A manufacturing method of a chip-type composite electronic component according to Claim 9, further comprising the steps of providing an intermediate insulating layer and laminating the inductor and the thermistor via the intermediate insulating layer.

Claims 15-20 (canceled)